

06-13-05

IFW 2827
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PATENT APPLICATION
Attorney Docket: 54364

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gupta, et al.
Serial No.: 09/847,667
Filed: 5/1/2001
For: Method for Bonding Wafers to
Produce Stacked Integrated
Circuits
Group Art Unit: 2827

Examiner: James Mitchell

PETITION FOR EXTENSION OF TIME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby petitions the Commissioner of Patents and Trademarks under 37 C.F.R. Sect. 1.136(a) to extend the time for response to the Office Action dated by 2 month(s). Applicant is small entity, and therefore believes the fee to be \$225.

The Commissioner is hereby authorized to charge all fees which may be required in this application under 37 C.F.R. Sect. 1.16-1.17 during its entire pendency, or credit any overpayment, to Deposit Account No. 23-0424. This petition is filed in duplicate.

I hereby certify that this paper is being deposited with the United States Postal as Express mail on the date signed below in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

06/15/2005 FFANAIA2 00000019 230424 09847667
01 FC:2252 225.00 DA

Respectfully submitted,

Calvin B. Ward
Registration No. 30,896

Dated: June 9, 2005

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